

line 15, after "other" insert --devices containing--.

Page 7, line 18, after "substrates" insert --in devices--.

Page 9, line 32, delete "including" and insert in place thereof --included in--.

Page 10, line 15, delete "including" and insert in place thereof --included in--.

Page 13, line 6, after "processing of" insert --substrates in--;

line 33, before "semiconductor" insert --substrates in--.

Page 19, line 32, after "examples," insert --substrates used in--.

Page 21, line 28, delete "which includes," and insert in place thereof --used in, for example,--.

Page 22, line 5, after "repair of" insert --substrates in--.

IN THE CLAIMS:

Please cancel Claim 1 and replace with new Claim 31:

1 --31. (New) An improved method for partially or completely removing organic coat-
2 ings, films, layers or residues from a substrate, said method comprising:

3 (1) subjecting said organic coatings, films, layers, or residues to a vapor con-
4 sisting essentially of water-free gaseous sulfur trioxide for a period of time, said substrates
5 being maintained at a temperature in the range from about room temperature to 400°C; and

6 (2) subjecting said organic coatings, films, layers, or residues to a solvent
7 rinse; *altered mat*

8 wherein the improvement comprises the following steps:

9 (a) providing organic coatings, films, layers and residues that are either photo-
10 sensitive or non-photosensitive organic materials and are selected from the group consisting
11 of polymerized photoresists, *paints, resins, single and multilayer organic polymers, organo-*

*Sub
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